

SINGLE RETRIGGERABLE MONOSTABLE MULTIVIBRATOR WITH SCHMITT-TRIGGER INPUTS

Check for Samples: [SN74LVC1G123](#)

FEATURES

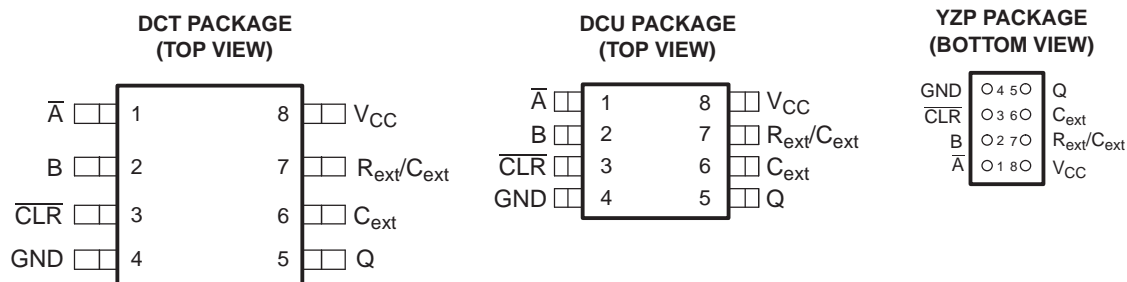
- Available in the Texas Instruments NanoFree™ Package
- Supports 5-V V_{CC} Operation
- Inputs Accept Voltages to 5.5 V
- Max t_{pd} of 8 ns at 3.3 V
- Supports Mixed-Mode Voltage Operation on All Ports
- Schmitt-Trigger Circuitry on \bar{A} and B Inputs for Slow Input Transition Rates
- Edge Triggered From Active-High or Active-Low Gated Logic Inputs
- Retriggerable for Very Long Output Pulses, up to 100% Duty Cycle
- Overriding Clear Terminates Output Pulse
- Glitch-Free Power-Up Reset on Outputs
- I_{off} Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

DESCRIPTION

The SN74LVC1G123 is a single retriggerable monostable multivibrator designed for 1.65-V to 5.5-V V_{CC} operation.

This monostable multivibrator features output pulse-duration control by three methods. In the first method, the \bar{A} input is low, and the B input goes high. In the second method, the B input is high, and the \bar{A} input goes low. In the third method, the \bar{A} input is low, the B input is high, and the clear (\overline{CLR}) input goes high.

The output pulse duration is programmed by selecting external resistance and capacitance values. The external timing capacitor must be connected between C_{ext} and R_{ext}/C_{ext} (positive) and an external resistor connected between R_{ext}/C_{ext} and V_{CC} . To obtain variable pulse durations, connect an external variable resistance between R_{ext}/C_{ext} and V_{CC} . The output pulse duration also can be reduced by taking \overline{CLR} low.



See mechanical drawings for dimensions.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of the Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

DESCRIPTION (CONTINUED)

Pulse triggering occurs at a particular voltage level and is not directly related to the transition time of the input pulse. The \bar{A} and B inputs have Schmitt triggers with sufficient hysteresis to handle slow input transition rates with jitter-free triggering at the outputs.

Once triggered, the basic pulse duration can be extended by retriggering the gated low-level-active (\bar{A}) or high-level-active (B) input. Pulse duration can be reduced by taking $\overline{\text{CLR}}$ low. $\overline{\text{CLR}}$ can be used to override \bar{A} or B inputs. The input/output timing diagram illustrates pulse control by retriggering the inputs and early clearing.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

NanoFree™ package technology is a major breakthrough in IC packaging concepts, using the die as the package.

FUNCTION TABLE

INPUTS			OUTPUTS
$\overline{\text{CLR}}$	\bar{A}	B	Q
L	X	X	L
X	H	X	L ⁽¹⁾
X	X	L	L ⁽¹⁾
H	L	↑	⌋
H	↓	H	⌋
↑	L	H	⌋

- (1) These outputs are based on the assumption that the indicated steady-state conditions at the A and B inputs have been set up long enough to complete any pulse started before the setup.

Figure 1. LOGIC DIAGRAM (POSITIVE LOGIC)

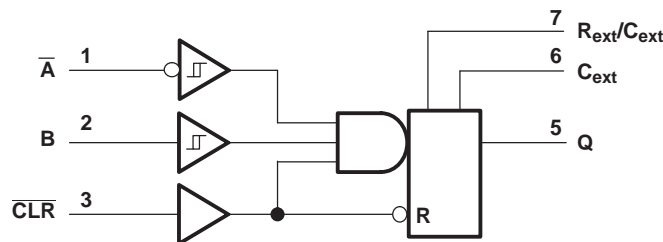


Figure 2. REQUIRED TIMING CIRCUIT

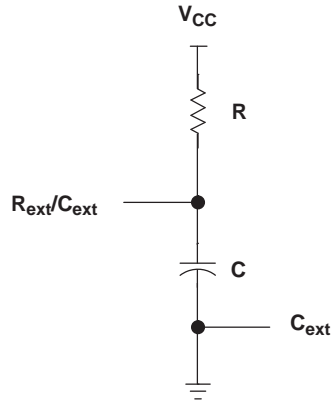
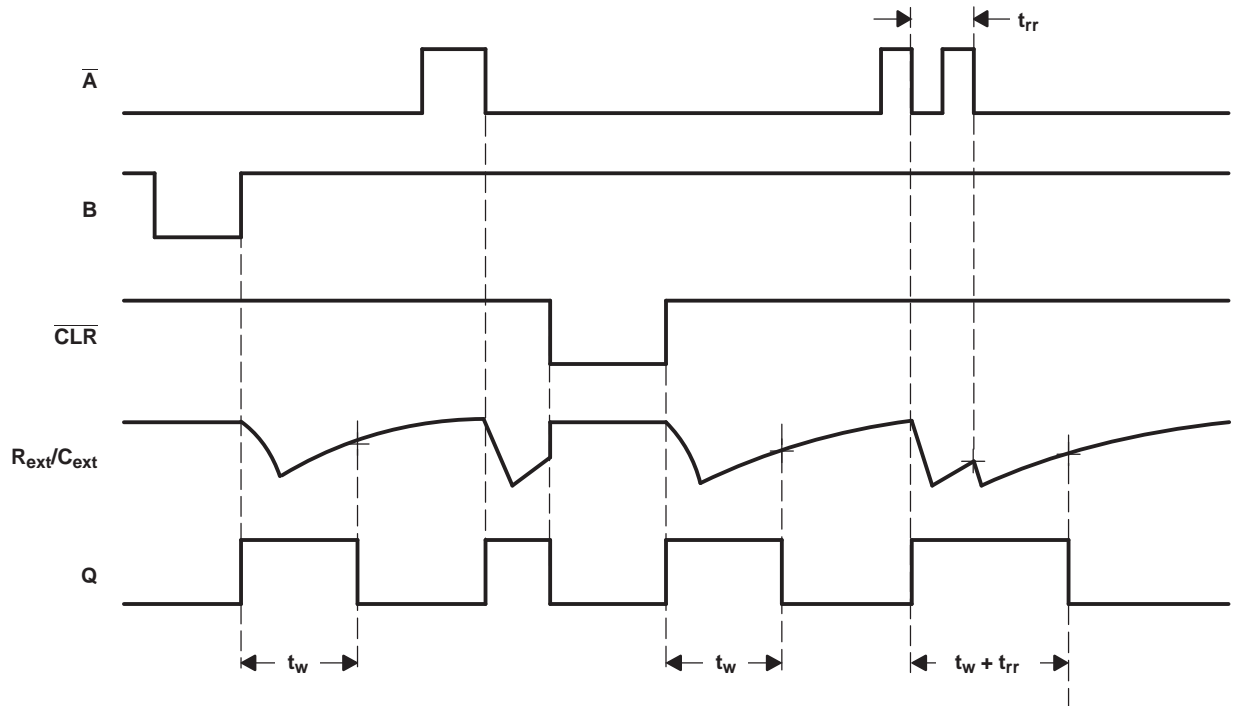


Figure 3. INPUT/OUTPUT TIMING DIAGRAM



Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V _{CC}	Supply voltage range	–0.5	6.5	V
V _I	Input voltage range ⁽²⁾	–0.5	6.5	V
V _O	Voltage range applied to any output in the high-impedance or power-off state ⁽²⁾	–0.5	6.5	V
V _O	Voltage range applied to any output in the high or low state ^{(2) (3)}	–0.5	V _{CC} + 0.5	V
I _{IK}	Input clamp current	V _I < 0	–50	mA
I _{OK}	Output clamp current	V _O < 0	–50	mA
I _O	Continuous output current		±50	mA
	Continuous current through V _{CC} or GND		±100	mA
θ _{JA}	Package thermal impedance ⁽⁴⁾	DCT package	220	°C/W
		DCU package	227	
		YZP package	102	
T _{stg}	Storage temperature range	–65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
- (3) The value of V_{CC} is provided in the recommended operating conditions table.
- (4) The package thermal impedance is calculated in accordance with JESD 51-7.

Recommended Operating Conditions⁽¹⁾

			MIN	MAX	UNIT
V _{CC}	Supply voltage	Operating	1.65	5.5	V
		Data retention only	1.5		
V _{IH}	High-level input voltage	V _{CC} = 1.65 V to 1.95 V	0.65 × V _{CC}		V
		V _{CC} = 2.3 V to 2.7 V	1.7		
		V _{CC} = 3 V to 3.6 V	2		
		V _{CC} = 4.5 V to 5.5 V	0.7 × V _{CC}		
V _{IL}	Low-level input voltage	V _{CC} = 1.65 V to 1.95 V		0.35 × V _{CC}	V
		V _{CC} = 2.3 V to 2.7 V		0.7	
		V _{CC} = 3 V to 3.6 V		0.8	
		V _{CC} = 4.5 V to 5.5 V		0.3 × V _{CC}	
V _I	Input voltage		0	5.5	V
V _O	Output voltage		0	V _{CC}	V
I _{OH}	High-level output current	V _{CC} = 1.65 V		–4	mA
		V _{CC} = 2.3 V		–8	
		V _{CC} = 3 V		–16	
				–24	
		V _{CC} = 4.5 V		–32	
I _{OL}	Low-level output current	V _{CC} = 1.65 V		4	mA
		V _{CC} = 2.3 V		8	
		V _{CC} = 3 V		16	
				24	
		V _{CC} = 4.5 V		32	
R _{ext} ⁽²⁾	External timing resistance	V _{CC} = 2 V	5 k		Ω
		V _{CC} ≥ 3 V	1 k		
T _A	Operating free-air temperature		–40	125	°C

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

(2) R_{ext}/C_{ext} is an I/O and must not be connected directly to GND or V_{CC}.

Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	–40°C to 85°C SN74LVC1G123			–40°C to 125°C SN74LVC1G123			UNIT
			MIN	TYP ⁽¹⁾	MAX	MIN	TYP ⁽¹⁾	MAX	
V _{OH}	I _{OH} = –100 μA	1.65 V to 5.5 V	V _{CC} – 0.1			V _{CC} – 0.1			V
	I _{OH} = –4 mA	1.65 V	1.2			1.2			
	I _{OH} = –8 mA	2.3 V	1.9			1.9			
	I _{OH} = –16 mA	3 V	2.4			2.4			
	I _{OH} = –24 mA		2.3			2.3			
	I _{OH} = –32 mA	4.5 V	3.8			3.8			
V _{OL}	I _{OL} = 100 μA	1.65 V to 5.5 V				0.1			V
	I _{OL} = 4 mA	1.65 V				0.45			
	I _{OL} = 8 mA	2.3 V				0.3			
	I _{OL} = 16 mA	3 V				0.4			
	I _{OL} = 24 mA					0.55			
	I _{OL} = 32 mA	4.5 V				0.55			
I _I	R _{ext} /C _{ext} ⁽²⁾ B = GND, $\overline{A} = \overline{CLR} = V_{CC}$	1.65 V to 5.5 V				±0.25			μA
	\overline{A} , B, \overline{CLR} V _I = 5.5 V or GND					±1			
I _{off}	\overline{A} , B, Q, \overline{CLR} V _I or V _O = 5.5 V	0				±10			μA
I _{CC}	Quiescent V _I = V _{CC} or GND, I _O = 0	5.5 V				20			μA
I _{CC}	Active state V _I = V _{CC} or GND, R _{ext} /C _{ext} = 0.5 V _{CC}	1.65 V				165			μA
		2.3 V				220			
		3 V				280			
		4.5 V				650			
		5.5 V				975			
C _I	V _I = V _{CC} or GND	3.3 V	3						pF

(1) All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

(2) This test is performed with the terminal in the off-state condition.

Timing Requirements

over recommended operating free-air temperature range (unless otherwise noted) (see [Figure 4](#))

PARAMETER	TEST CONDITIONS	SN74LVC1G123 –40°C to 85°C								UNIT	
		V _{CC} = 1.8 V ± 0.15 V		V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 5 V ± 0.5 V			
		MIN	TYP	MIN	TYP	MIN	TYP	MIN	TYP		
t _W IN	Pulse duration \overline{CLR} or \overline{A} or B trigger	8		4		3		2.5		ns	
		8		4		3		2.5			
t _{rr}	Pulse retrigger time	R _{ext} = 1 kΩ	C _{ext} = 100 pF				5.5		4.5	ns	
			C _{ext} = 100 μF				1.4		1.1	μs	
		R _{ext} = 5 kΩ	C _{ext} = 100 pF	75		45					ns
			C _{ext} = 100 μF	1.8		1.4					μs

Timing Requirements

 over recommended operating free-air temperature range (unless otherwise noted) (see [Figure 4](#))

PARAMETER		TEST CONDITIONS	SN74LVC1G123 –40°C to 125°C								UNIT
			V _{CC} = 1.8 V ± 0.15 V		V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 5 V ± 0.5 V		
			MIN	TYP	MIN	TYP	MIN	TYP	MIN	TYP	
t _w IN	Pulse duration	$\overline{\text{CLR}}$	8		4		3		2.5		ns
		$\overline{\text{A}}$ or B trigger	8		4		3		2.5		
t _{rr}	Pulse retrigger time	R _{ext} = 1 kΩ	C _{ext} = 100 pF				5.5		4.5		ns
			C _{ext} = 100 μF				1.4		1.1		μs
		R _{ext} = 5 kΩ	C _{ext} = 100 pF		75		45				ns
			C _{ext} = 100 μF		1.8		1.4				μs

Switching Characteristics

 over recommended operating free-air temperature range, C_L = 15 pF (unless otherwise noted) (see [Figure 4](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74LVC1G123 –40°C to 85°C								UNIT	
			V _{CC} = 1.8 V ± 0.15 V			V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 5 V ± 0.5 V		
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	MIN		MAX
t _{pd}	$\overline{\text{A}}$ or B	Q	7	18.5	52	4	17	3	11.5	2	7.6	ns
	$\overline{\text{CLR}}$		5	12.4	34	3	11.5	2	8	1.5	5.5	
	$\overline{\text{CLR}}$ trigger		7	17.4	54	4	15.5	3	10.5	2	7	

Switching Characteristics

 over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see [Figure 5](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	SN74LVC1G123 –40°C to 85°C								UNIT	
				V _{CC} = 1.8 V ± 0.15 V			V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 5 V ± 0.5 V		
				MIN	TYP ⁽¹⁾	MAX	MIN	MAX	MIN	MAX	MIN		MAX
t _{pd}	$\overline{\text{A}}$ or B	Q		6	18.6	57	3	18.5	2	12.5	1.5	8.2	ns
	$\overline{\text{CLR}}$		4	11.6	36.5	2	12.5	1.5	8.6	1.5	6		
	$\overline{\text{CLR}}$ trigger		5	17.3	59	2.5	17	2	11.5	1.5	7.5		
t _w OUT ⁽²⁾		Q	C _{ext} = 28 pF, R _{ext} = 2 kΩ		225	600	190	220	170	200	150	180	ns
			C _{ext} = 0.01 μF, R _{ext} = 10 kΩ		100	110	100	110	100	110	100	110	μs
			C _{ext} = 0.1 μF, R _{ext} = 10 kΩ		1	1.1	1	1.1	1	1.1	1	1.1	ms

 (1) T_A = 25°C

 (2) t_w = Duration of pulse at Q output

Switching Characteristics

over recommended operating free-air temperature range, $C_L = 50$ pF (unless otherwise noted) (see Figure 5)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	SN74LVC1G123 –40°C to 125°C								UNIT	
				$V_{CC} = 1.8$ V ± 0.15 V			$V_{CC} = 2.5$ V ± 0.2 V		$V_{CC} = 3.3$ V ± 0.3 V		$V_{CC} = 5$ V ± 0.5 V		
				MIN	TYP ⁽¹⁾	MAX	MIN	MAX	MIN	MAX	MIN		MAX
t_{pd}	\bar{A} or B	Q		6		58	3	19.5	2	13.2	1.5	8.7	ns
	\overline{CLR}			4		37	2	13.5	1.5	9.2	1.5	6.5	
	\overline{CLR} trigger			5		60	2.5	18	2	12	1.5	8	
$t_{wOUT}^{(2)}$		Q	$C_{ext} = 28$ pF, $R_{ext} = 2$ k Ω		225	600	190	220	170	200	150	180	ns
			$C_{ext} = 0.01$ μ F, $R_{ext} = 10$ k Ω		100	110	100	110	100	110	100	110	μ s
			$C_{ext} = 0.1$ μ F, $R_{ext} = 10$ k Ω		1	1.1	1	1.1	1	1.1	1	1.1	ms

(1) $T_A = 25^\circ\text{C}$

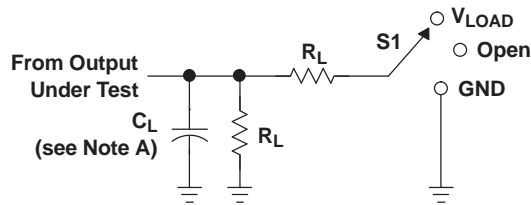
(2) t_w = Duration of pulse at Q output

Operating Characteristics

$T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	$V_{CC} = 1.8$ V	$V_{CC} = 2.5$ V	$V_{CC} = 3.3$ V	$V_{CC} = 5$ V	UNIT
		TYP	TYP	TYP	TYP	
C_{pd} Power dissipation capacitance	$\bar{A} = \text{low}, B = \text{high},$ $\overline{CLR} = 10$ MHz			35	37	pF
		$R_{ext} = 1$ k Ω , No C_{ext}				
		41	40			
	$R_{ext} = 5$ k Ω , No C_{ext}					

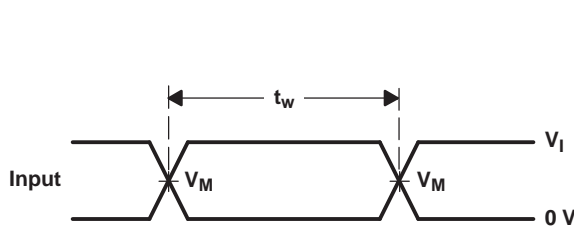
PARAMETER MEASUREMENT INFORMATION



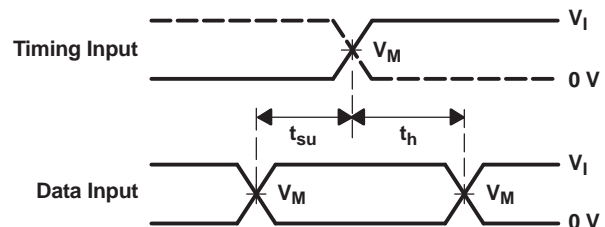
LOAD CIRCUIT

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	V_{LOAD}
t_{PHZ}/t_{PZH}	GND

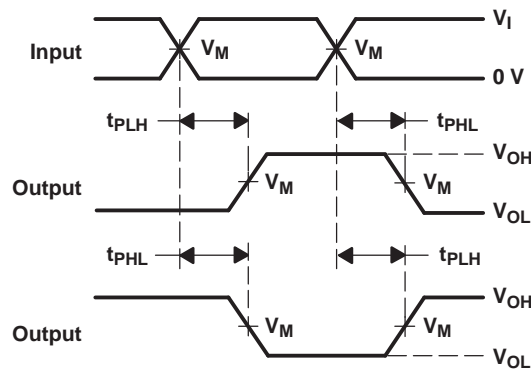
V_{CC}	INPUTS		V_M	V_{LOAD}	C_L	R_L	V_{Δ}
	V_I	t_r/t_f					
$1.8\text{ V} \pm 0.15\text{ V}$	V_{CC}	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	15 pF	1 M Ω	0.15 V
$2.5\text{ V} \pm 0.2\text{ V}$	V_{CC}	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	15 pF	1 M Ω	0.15 V
$3.3\text{ V} \pm 0.3\text{ V}$	3 V	$\leq 2.5\text{ ns}$	1.5 V	6 V	15 pF	1 M Ω	0.3 V
$5\text{ V} \pm 0.5\text{ V}$	V_{CC}	$\leq 2.5\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	15 pF	1 M Ω	0.3 V



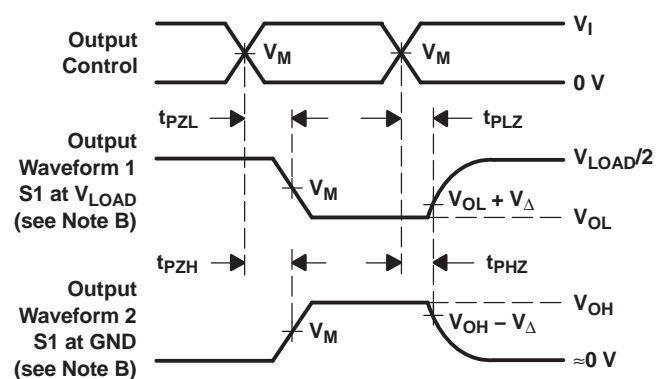
VOLTAGE WAVEFORMS PULSE DURATION



VOLTAGE WAVEFORMS SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS PROPAGATION DELAY TIMES INVERTING AND NONINVERTING OUTPUTS

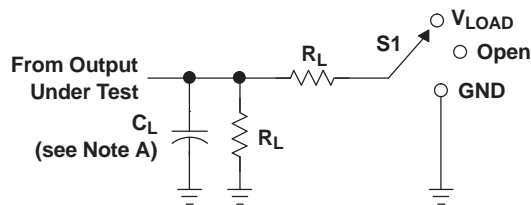


VOLTAGE WAVEFORMS ENABLE AND DISABLE TIMES LOW- AND HIGH-LEVEL ENABLING

- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10\text{ MHz}$, $Z_O = 50\ \Omega$.
 - D. The outputs are measured one at a time, with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .
 - H. All parameters and waveforms are not applicable to all devices.

Figure 4. Load Circuit and Voltage Waveforms

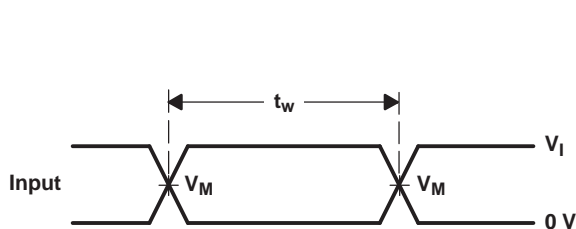
PARAMETER MEASUREMENT INFORMATION



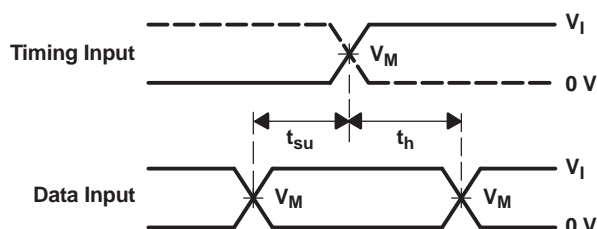
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	V_{LOAD}
t_{PHZ}/t_{PZH}	GND

LOAD CIRCUIT

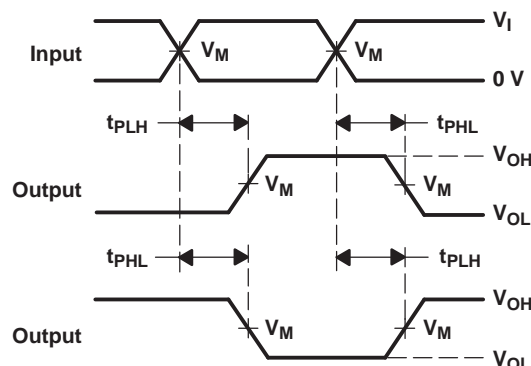
V_{CC}	INPUTS		V_M	V_{LOAD}	C_L	R_L	V_{Δ}
	V_I	t_r/t_f					
$1.8\text{ V} \pm 0.15\text{ V}$	V_{CC}	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	1 k Ω	0.15 V
$2.5\text{ V} \pm 0.2\text{ V}$	V_{CC}	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	500 Ω	0.15 V
$3.3\text{ V} \pm 0.3\text{ V}$	3 V	$\leq 2.5\text{ ns}$	1.5 V	6 V	50 pF	500 Ω	0.3 V
$5\text{ V} \pm 0.5\text{ V}$	V_{CC}	$\leq 2.5\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	50 pF	500 Ω	0.3 V



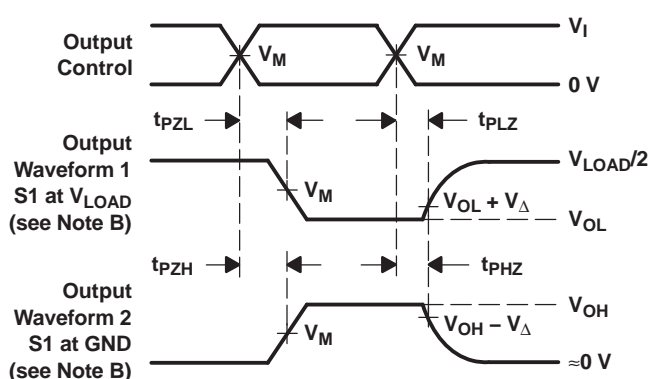
VOLTAGE WAVEFORMS PULSE DURATION



VOLTAGE WAVEFORMS SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS PROPAGATION DELAY TIMES INVERTING AND NONINVERTING OUTPUTS



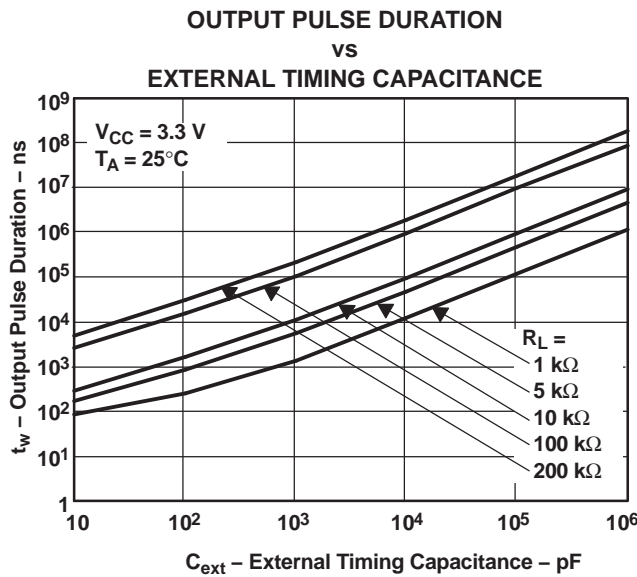
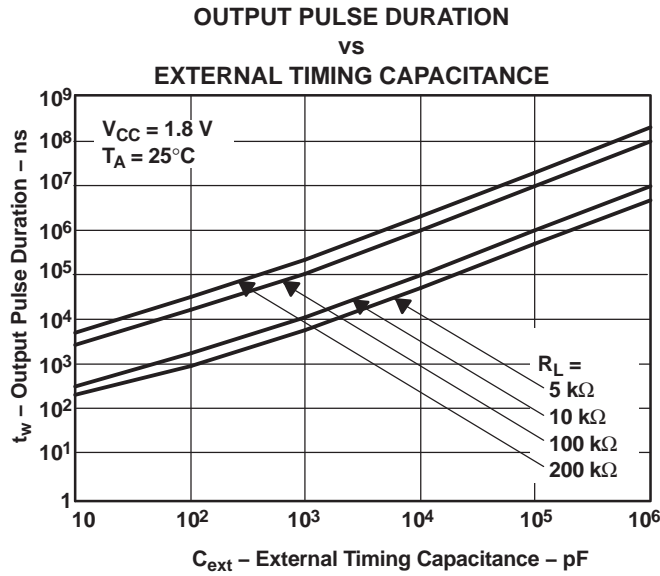
VOLTAGE WAVEFORMS ENABLE AND DISABLE TIMES LOW- AND HIGH-LEVEL ENABLING

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 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .
 - H. All parameters and waveforms are not applicable to all devices.

Figure 5. Load Circuit and Voltage Waveforms

APPLICATION INFORMATION

Operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied.



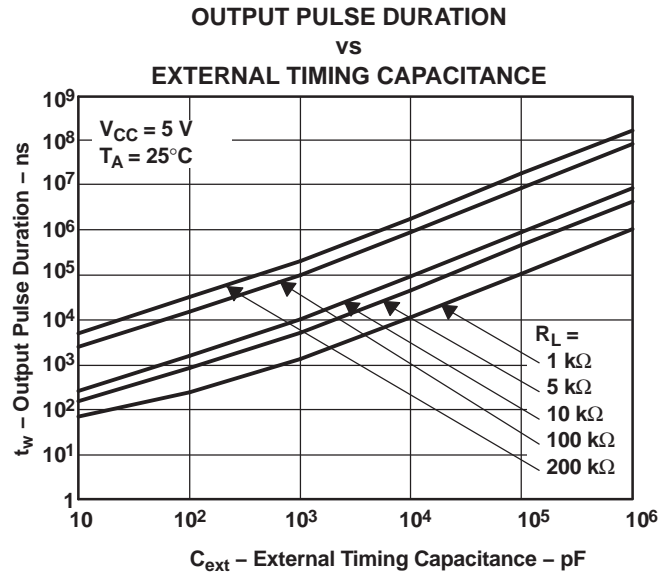


Figure 8.

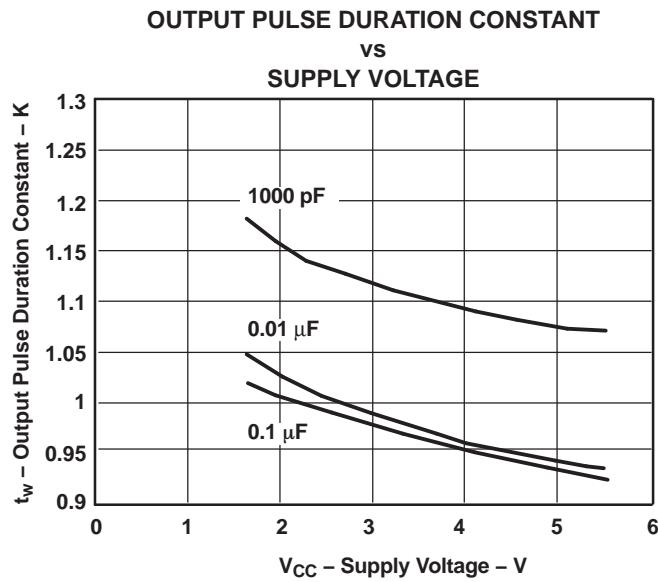
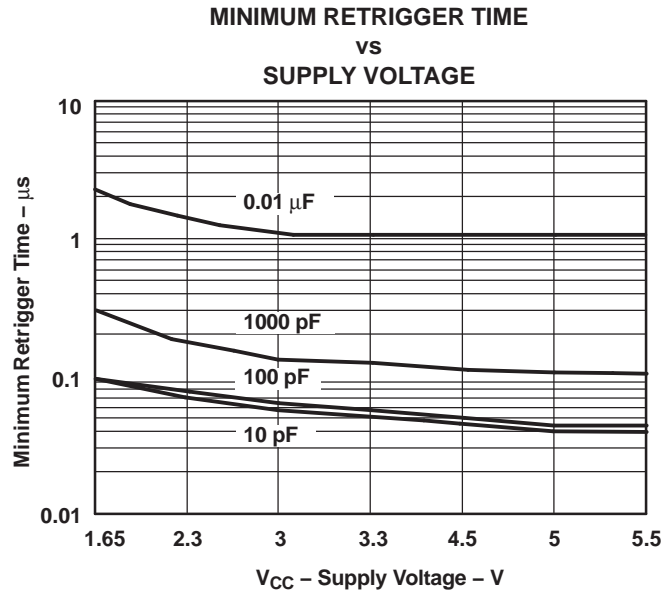


Figure 9.



REVISION HISTORY

Changes from Revision B (January 2007) to Revision C	Page
• Updated document to new TI datasheet format - no specification changes	1
• Removed Ordering Information table.	2
• Updated operating temperature range.	5

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
74LVC1G123DCTRE4	ACTIVE	SM8	DCT	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	C23 Z	Samples
74LVC1G123DCTRG4	ACTIVE	SM8	DCT	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	C23 Z	Samples
74LVC1G123DCTTE4	ACTIVE	SM8	DCT	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	C23 Z	Samples
74LVC1G123DCTTG4	ACTIVE	SM8	DCT	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	C23 Z	Samples
74LVC1G123DCURE4	ACTIVE	US8	DCU	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	(C23Q ~ C23R)	Samples
74LVC1G123DCURG4	ACTIVE	US8	DCU	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	(C23Q ~ C23R)	Samples
74LVC1G123DCUTE4	ACTIVE	US8	DCU	8		TBD	Call TI	Call TI	-40 to 125	(C23Q ~ C23R)	Samples
74LVC1G123DCUTG4	ACTIVE	US8	DCU	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	(C23Q ~ C23R)	Samples
SN74LVC1G123DCTR	ACTIVE	SM8	DCT	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	C23 Z	Samples
SN74LVC1G123DCTT	ACTIVE	SM8	DCT	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	C23 Z	Samples
SN74LVC1G123DCUR	ACTIVE	US8	DCU	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU CU SN	Level-1-260C-UNLIM	-40 to 125	(C23Q ~ C23R)	Samples
SN74LVC1G123DCUT	ACTIVE	US8	DCU	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU CU SN	Level-1-260C-UNLIM	-40 to 125	(C23Q ~ C23R)	Samples
SN74LVC1G123YZPR	ACTIVE	DSBGA	YZP	8	3000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 85	(D87 ~ D8N)	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVC1G123DCUR	US8	DCU	8	3000	180.0	8.4	2.25	3.35	1.05	4.0	8.0	Q3
SN74LVC1G123YZPR	DSBGA	YZP	8	3000	178.0	9.2	1.02	2.02	0.63	4.0	8.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVC1G123DCUR	US8	DCU	8	3000	202.0	201.0	28.0
SN74LVC1G123YZPR	DSBGA	YZP	8	3000	220.0	220.0	35.0

DCT (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Publication IPC-7351 is recommended for alternate designs.
 D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

DCU (S-PDSO-G8)

PLASTIC SMALL OUTLINE PACKAGE (DIE DOWN)

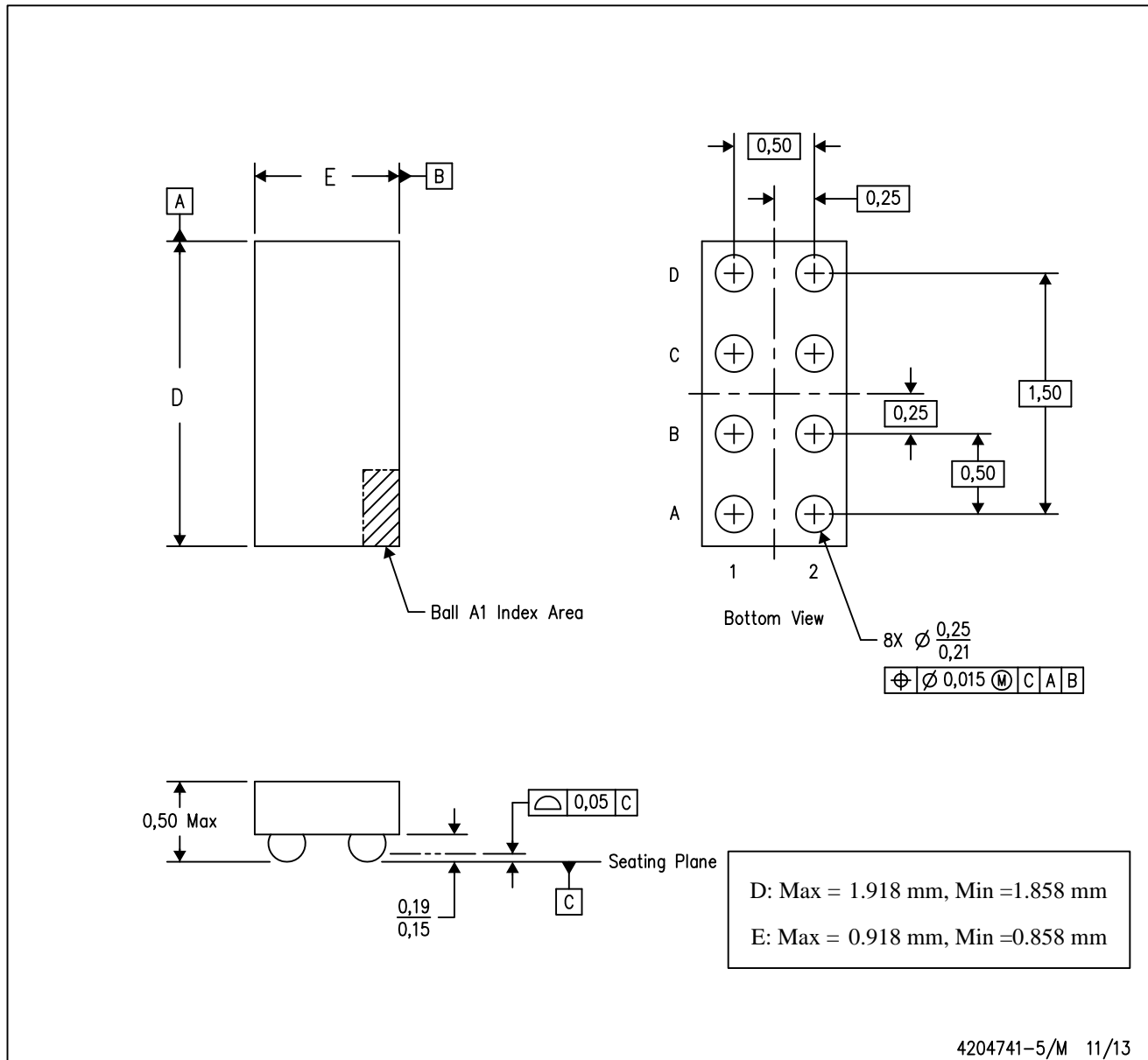


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- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

YZP (R-XBGA-N8)

DIE-SIZE BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. NanoFree™ package configuration.

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